

TITLE OF THE INVENTION: METHOD AND AN APPARATUS FOR FORMING AN ELECTRONIC DEVICE

Abstract

A method and an apparatus for forming an electronic device is provided. The method comprises: providing a substrate; disposing at least one electronic component on the substrate via a solder paste; applying microwave radiation to the substrate to reflow the solder paste; applying a vacuum pressure to the substrate to remove voids formed within the solder paste during the reflowing of the solder paste; solidifying the solder paste into solder bumps between the substrate and the at least one electronic component.

[FIG. 2]